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ASC_WQPM444220 Series

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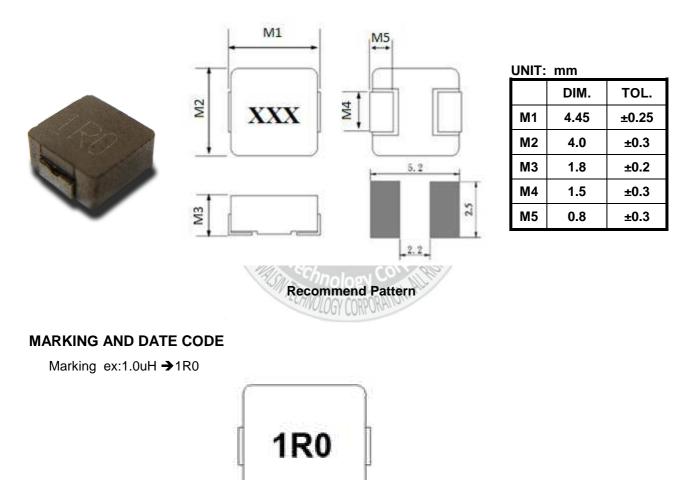
Features

- 1. Shielded construction.
- 2. Ultra low buzz noise.
- 3. Low DCR/ μ H.
- 4. Handles high transient current spikes without saturation.
- 5. Encapsulated body offers improved environmental protection and moisture resistance.
- 6. Higher dielectric withstanding voltage.
- 7. Corrosion resistant package.
- 8. RoHS Compliance.

Applications

- 1. PDA/Notebook/Desktop/Server applications high current and low profile power supplier
- 2. High current POL converters.
- 3. Battery powered devices.

SHAPE and DIMENSION





Ordering Information

WQ	РМ	4442	20	м	R10	L	С
Product Code	Series	Dimensions	Thickness	Tolerance	Value	Packing Code	
WQ: Inductor AEC- Q200	SMD molded power inductor.	4.4 * 4.0mm	1.8mm	M: ± 20%	R10=0.10uH 1R0=1.0uH 100=10.0uH	L=13" Reeled (Embossed tape)	C:

Electrical Characteristics

Part number	Inductance (uH)		sistance nΩ)	Rated Current (A)	l sat (A) Typical	
	±20%	Typical	Max	Typical		
WQPM444220MR10LC	0.10	3.5	4.0	12.0	22.0	
WQPM444220MR22LC	0.22	6.0	6.6	9.0	12.5	
WQPM444220MR33LC	0.33	9.6	13	8.0	12.0	
WQPM444220MR47LC	0.47	12.5	14	7.0	9.5	
WQPM444220MR56LC	0.56	F14.0 7	16	6.5	10.0	
WQPM444220MR68LC	0.68	< \16.0\ _{>}	18	6.0	9.0	
WQPM444220M1R0LC	1.0 ××	24.0	/ 27	4.5	7.0	
WQPM444220M1R2LC	1.2	24.0	27	4.5	7.0	
WQPM444220M1R5LC	1.5	38.0	46	4.0	6.0	
WQPM444220M2R2LC	2.2	52.0	58	3.0	5.0	
WQPM444220M3R3LC	8 3.3 PASSIN	74.0	87 Q	2.5	4.0	
WQPM444220M4R7LC	4.7	98.0	110	2.2	3.5	
WQPM444220M5R6LC	5.6	105	115	1.8	3.5	
WQPM444220M6R8LC	6.8	160	175	1.5	2.5	
WQPM444220M100LC	10 TECHN	256	282	1.2	2.2	

CLUGY CORPORATIO

NOTE

1. TOLERANCE: M ±20%

2. INDUCTANCE VI RMS VI SAT MEASURED AN HP4284A, CH11025, CH3302, CH1320, CH1320S LCR METER.

3. DCR MESASURED USING A CH16502.

- 4. CURRENT THAT CAUSES A 15°C TEMPERATURE RISE FROM 25°C AMBIENT.
- 5. ELECTRICAL SPECIFICATIONS AT 25°C.
- 6. OPERATING TEMPERATURE: -40°C ~ +125°C .
- 7. STORAGE TEMPERATURE COMPONENT: -40°C to +100°C. TAPE AND REEL PACKING : -40°C to +80°C.

8. MOISTURE SENSITIVITY LEVEL (MSL) 1 (UNLIMITED FLOOR LIFE AT < 30°C / 85% RELATIVE HUMIDITY)

9. GRAPHIC IS ONLY FOR DIMENSIONALLY APPLICATION.



RELIABILITY PERFORMANCE

Test Item	Accept criteria	Test Condition	Standard Source	
High Temperature Exposure (Storage)	 Change from an initial value L:within±20% 2.no visible damage. 	1000 hrs. at rated operating temperature (e.g. 125° C part can be stored for 1000 hrs. @ 125° C. Same applies fo r 105 $^{\circ}$ C and 85 $^{\circ}$ C. Unpowered. Measurement at 24±4 hours after test conclusion.	MIL-STD-202 Method 108	
Temperature Cycling	 Change from an initial value L:within±20% 2.no visible damage. 	1000 cycles (-40 $^{\circ}$ to +125 $^{\circ}$). Note: If 85 $^{\circ}$ part or r 105 $^{\circ}$ part the 1000 cycles will be at that temperat ure. Measurement at 24±4 hours after test conclusion. 30min maximum dwell time at each temperature extreme. 1 min. maximum transition time.	JESD22 Method JA-104	
		1000 hours 85℃/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.	MIL-STD-202 Method 103	
Operational Life 2.no visible damage.		1000 hrs. @ 105°C. If 85°C or 125°C part will be te sted at that temperature. Measurement at 24±4 hours after test conclusion.	MIL-PRF-27	
Mechanical Shock	1.Within product specification tolerance 2.no visible damage.	Method 213. Condition C, Peak Value: 100g's, Duration: 6ms, Waveform: Half-sine Velocity Change: 12.3ft/sec	MIL-STD-202 Method 213	
Vibration	1.Change from an initial value L:within±20% 2.no visible damage.	5g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	MIL-STD-202 Method 204	
Resistance to Soldering Heat	1.No visible damage.	Condition B No pre-heat of samples. Note: Single Wave Solder - Procedure 2 for SMD and Procedure 1 for Leaded with solder within 1.5mm of device body.	MIL-STD-202 Method 210	
ESD	 Change from an initial value L:within±20% 2.no visible damage. 	Passive Component Human Body Model (HBM) Electrostatic Discharge (ESD) Test. Only direct contact discharge, record the voltage value what the sample can pass.	AEC-Q200-002 Or ISO/DIS10605	
Solderability	1.95% coverage min. good tinning. 2.no visible damage.	For both Leaded & SMD. Electrical Test not required. Magnification 50X. Conditions: Leaded: Method A @ 235°C, category 3. SMD: a) Method B, 4 hrs @ 155°C dry heat @ 235°C b) Method B @ 215°C category 3. c) Method D category 3 @ 260°C.	J-STD-002	

RELIABILITY PERFORMANCE

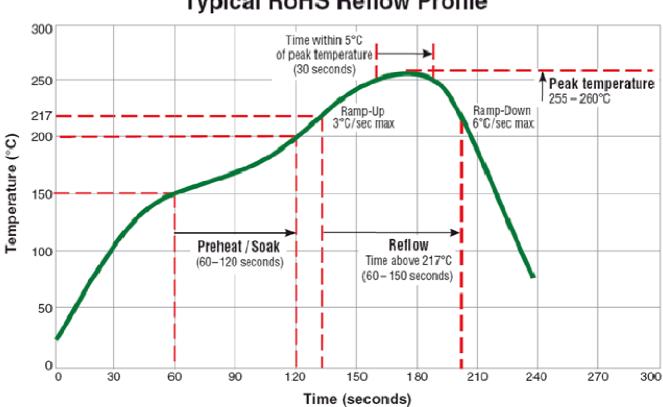
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Test Item	Accept criteria	Test Condition	Standard Source	
Flammability	1.Meet UL94V-0 or V1.	V-0 or V-1 Acceptable	UL-94	
	1.No drop. 2.no solder connect broken.	60 sec minimum holding time.	AEC-Q200-005	
	 No cracking. no part being sheared off from its pad. 	Force of 1.8kg for 60 seconds.	AEC-Q200-006	

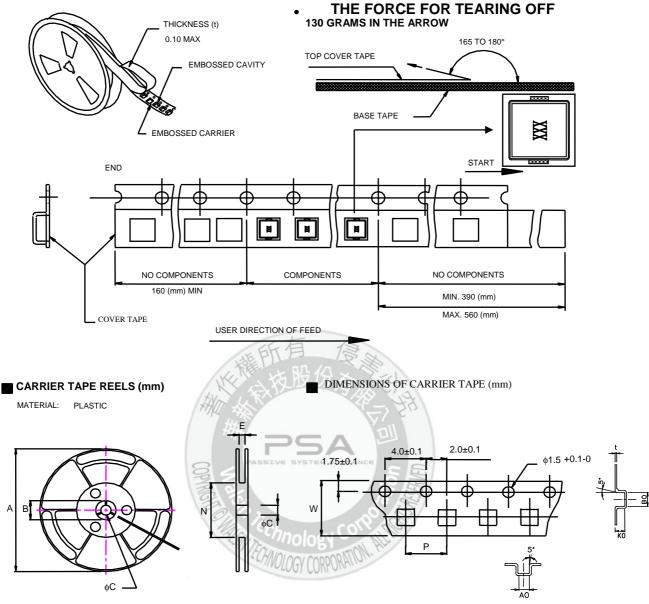
TYPICAL RoHS REFLOW PROFILE



Typical RoHS Reflow Profile



Packaging



% 10 sprocket hole pitch cumulative tolerance ± 0.20

UNIT : mm

	Α	В	С	Е	Ν	Р	W	t	A0	B0	K0
DIM.	330	25.0	13.5	13.0	100	8.0	12.0	0.3	4.7	4.4	2.5
TOL.	±0.2	±0.5	±0.5	±0.5	MIN	±0.1	±0.3	±0.05	±0.1	±0.1	±0.1

Quantity per reel : 2K pcs